

ABSTRACT OF THE DISCLOSURE

In the sawing process and device according to the invention, the pieces to be sawed are mounted on at least
5 one support table and caused to bear against a layer of wires. Inclination structure in the form of wedges or pieces for angular adjustment by pivoting and blocking, are provided to mount the pieces obliquely with angles of inclination between one of their prismatic surfaces and a
10 horizontal working plane. There is thus obtained a precise beginning of sawing with sawed slices of equal thickness and a careful end of cutting without chipping.